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MicroConverter 12-Bit ADCs and DACs with Embedded High Speed 62 kB Flash MCU

Data Sheet

ADuC841/ADuC842/ADuC843

FEATURES

Pin compatible upgrade of ADuC812/ADuC831/ADuC832
- **Increased performance**
  - **Single-cycle 20 MIPS 8052 core**
  - **High speed 420 kSPS 12-bit ADC**
- **Increased memory**
  - **Up to 62 kBytes on-chip Flash/EE program memory**
  - **4 kBytes on-chip Flash/EE data memory**
- **In-circuit reprogrammable**
  - **Flash/EE, 100 year retention, 100 kCycle endurance**
  - **2304 bytes on-chip data RAM**
- **Smaller package**
  - **8 mm × 8 mm chip scale package**
  - **52-lead PQFP—pin-compatible upgrade**

Analog I/O
- **8-channel, 420 kSPS high accuracy, 12-bit ADC**
- **On-chip, 15 ppm/°C voltage reference**
- **DMA controller, high speed ADC-to-RAM capture**
- **Two 12-bit voltage output DACs[1]**
- **Dual output PWM Σ-Δ DACs**
- **On-chip temperature monitor function**

8052 based core
- **8051 compatible instruction set (20 MHz max)**

High performance single-cycle core
- **32 kHz external crystal, on-chip programmable PLL**
- **12 interrupt sources, 2 priority levels**
- **Dual data pointers, extended 11-bit stack pointer**

On-chip peripherals
- **Time interval counter (TIC)**
- **UART, I²C®, and SPI® Serial I/O**
- **Watchdog timer (WDT)**
- **Power supply monitor (PSM)**

Power
- **Normal: 4.5 mA @ 3 V (core CLK = 2.098 MHz)**
- **Power-down: 10 µA @ 3 V[2]**

Development tools
- **Low cost, comprehensive development system incorporating nonintrusive single-pin emulation,**
- **IDE based assembly and C source debugging**

APPLICATIONS

Optical networking—laser power control
Base station systems
Precision instrumentation, smart sensors
Transient capture systems
DAS and communications systems

[1] ADuC841/ADuC842 only.
[2] ADuC842/ADuC843 only, ADuC841 driven directly by external crystal.

FUNCTIONAL BLOCK DIAGRAM

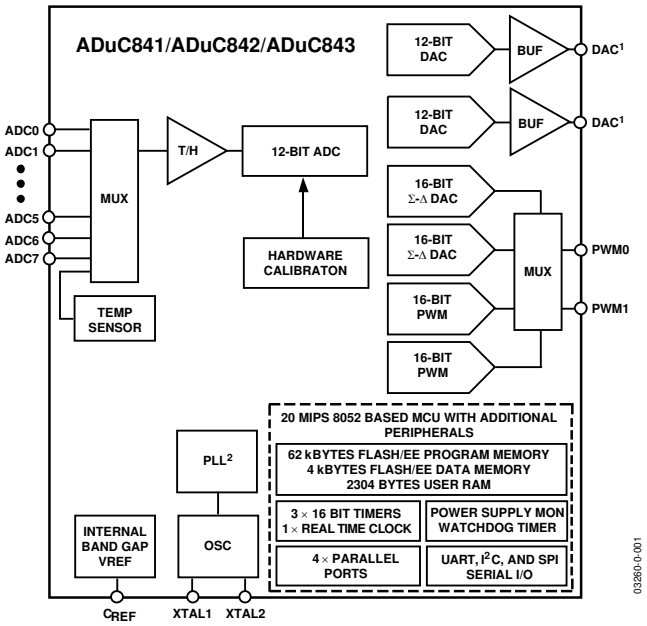

Figure 1.

GENERAL DESCRIPTION

The ADuC841/ADuC842/ADuC843[1] are complete smart transducer front ends, that integrates a high performance self-calibrating multichannel ADC, a dual DAC, and an optimized single-cycle 20 MHz 8-bit MCU (8051 instruction set compatible) on a single chip.

The ADuC841 and ADuC842 are identical with the exception of the clock oscillator circuit; the ADuC841 is clocked directly from an external crystal up to 20 MHz whereas the ADuC842 uses a 32 kHz crystal with an on-chip PLL generating a programmable core clock up to 16.78 MHz.

The ADuC843 is identical to the ADuC842 except that the ADuC843 has no analog DAC outputs.

The microcontroller is an optimized 8052 core offering up to 20 MIPS peak performance. Three different memory options are available offering up to 62 kBytes of nonvolatile Flash/EE program memory. Four kBytes of nonvolatile Flash/EE data memory, 256 bytes RAM, and 2 kBytes of extended RAM are also integrated on-chip.

[1] Protected by U.S. Patent No. 5,969,657.

(continued on page 15)

Rev. A **Document Feedback**

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REVISION HISTORY

4/16—Rev. 0 to Rev. A

Added Patent Note, Note 1 ... 1
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Added Table 4; Renumbered Sequentially ... 14
Changes to Using the DAC Section ... 47
Updated Outline Dimensions ... 94
Changes to Ordering Guide ... 95

11/03—Revision 0: Initial Version

SPECIFICATIONS[1]

Table 1. AV_{DD} = DV_{DD} = 2.7 V to 3.6 V or 4.75 V to 5.25 V; V_{REF} = 2.5 V internal reference, f_{CORE} = 16.78 MHz @ 5 V 8.38 MHz @ 3 V; all specifications T_A = T_{MIN} to T_{MAX}, unless otherwise noted

Parameter	V_{DD} = 5 V	V_{DD} = 3 V	Unit	Test Conditions/Comments
ADC CHANNEL SPECIFICATIONS				
DC ACCURACY[2, 3]				f_{SAMPLE} = 120 kHz, see the Typical Performance Characteristics for typical performance at other values of f_{SAMPLE}
Resolution	12	12	Bits	
Integral Nonlinearity	±1	±1	LSB max	2.5 V internal reference
	±0.3	±0.3	LSB typ	
Differential Nonlinearity	+1/−0.9	+1/−0.9	LSB max	2.5 V internal reference
	±0.3	±0.3	LSB typ	
Integral Nonlinearity[4]	±2	±1.5	LSB max	1 V external reference
Differential Nonlinearity[4]	+1.5/−0.9	+1.5/−0.9	LSB max	1 V external reference
Code Distribution	1	1	LSB typ	ADC input is a dc voltage
CALIBRATED ENDPOINT ERRORS[5, 6]				
Offset Error	±3	±2	LSB max	
Offset Error Match	±1	±1	LSB typ	
Gain Error	±3	±2	LSB max	
Gain Error Match	±1	±1	LSB typ	
DYNAMIC PERFORMANCE				f_{IN} = 10 kHz sine wave f_{SAMPLE} = 120 kHz
Signal-to-Noise Ratio (SNR)[7]	71	71	dB typ	
Total Harmonic Distortion (THD)	−85	−85	dB typ	
Peak Harmonic or Spurious Noise	−85	−85	dB typ	
Channel-to-Channel Crosstalk[8]	−80	−80	dB typ	
ANALOG INPUT				
Input Voltage Range	0 to V_{REF}	0 to V_{REF}	V	
Leakage Current	±1	±1	µA max	
Input Capacitance	32	32	pF typ	
TEMPERATURE SENSOR[9]				
Voltage Output at 25°C	700	700	mV typ	
Voltage TC	−1.4	−1.4	mV/°C typ	
Accuracy	±1.5	±1.5	°C typ	Internal/External 2.5 V V_{REF}
DAC CHANNEL SPECIFICATIONS **Internal Buffer Enabled** ADuC841/ADuC842 **Only**				DAC load to AGND R_L = 10 kΩ, C_L = 100 pF
DC ACCURACY[10]				
Resolution	12	12	Bits	
Relative Accuracy	±3	±3	LSB typ	
Differential Nonlinearity[11]	−1	−1	LSB max	Guaranteed 12-bit monotonic
	±1/2	±1/2	LSB typ	
Offset Error	±50	±50	mV max	V_{REF} range
Gain Error	±1	±1	% max	AV_{DD} range
	±1	±1	% typ	V_{REF} range
Gain Error Mismatch	0.5	0.5	% typ	% of full-scale on DAC1
ANALOG OUTPUTS				
Voltage Range_0	0 to V_{REF}	0 to V_{REF}	V typ	DAC V_{REF} = 2.5 V
Voltage Range_1	0 to V_{DD}	0 to V_{DD}	V typ	DAC V_{REF} = V_{DD}
Output Impedance	0.5	0.5	Ω typ	

Parameter	V_{DD} = 5 V	V_{DD} = 3 V	Unit	Test Conditions/Comments
DAC AC CHARACTERISTICS				
Voltage Output Settling Time	15	15	µs typ	Full-scale settling time to within ½ LSB of final value
Digital-to-Analog Glitch Energy	10	10	nV-sec typ	1 LSB change at major carry
DAC CHANNEL SPECIFICATIONS[12, 13]				
Internal Buffer Disabled ADuC841/ADuC842 Only				
DC ACCURACY[10]				
Resolution	12	12	Bits	
Relative Accuracy	±3	±3	LSB typ	
Differential Nonlinearity[11]	–1	–1	LSB max	Guaranteed 12-bit monotonic
	±1/2	±1/2	LSB typ	
Offset Error	±5	±5	mV max	V_{REF} range
Gain Error	±0.5	±0.5	% typ	V_{REF} range
Gain Error Mismatch[4]	0.5	0.5	% typ	% of full-scale on DAC1
ANALOG OUTPUTS				
Voltage Range_0	0 to V_{REF}	0 to V_{REF}	V typ	DAC V_{REF} = 2.5 V
REFERENCE INPUT/OUTPUT REFERENCE OUTPUT[14]				
Output Voltage (V_{REF})	2.5	2.5	V	
Accuracy	±10	±10	mV Max	Of V_{REF} measured at the C_{REF} pin T_A = 25°C
Power Supply Rejection	65	67	dB typ	
Reference Temperature Coefficient	±15	±15	ppm/°C typ	
Internal V_{REF} Power-On Time	2	2	ms typ	
EXTERNAL REFERENCE INPUT[15]				
Voltage Range (V_{REF}) [4]	1	1	V min	
	V_{DD}	V_{DD}	V max	
Input Impedance	20	20	kΩ typ	
Input Leakage	1	1	µA max	Internal band gap deselected via ADCCON1.6
POWER SUPPLY MONITOR (PSM)				
DV_{DD} Trip Point Selection Range		2.93	V min	Two trip points selectable in this range programmed via TPD1–0 in PSMCON, 3 V part only
		3.08	V max	
DV_{DD} Power Supply Trip Point Accuracy		±2.5	% max	
WATCHDOG TIMER (WDT) [4]				
Timeout Period	0	0	ms min	Nine timeout periods selectable in this range
	2000	2000	ms max	
FLASH/EE MEMORY RELIABILITY CHARACTERISTICS[16]				
Endurance[17]	100,000	100,000	Cycles min	
Data Retention[18]	100	100	Years min	
DIGITAL INPUTS				
Input Leakage Current (Port 0, $\overline{EA}$)	±10	±10	µA max	V_{IN} = 0 V or V_{DD}
	±1	±1	µA typ	V_{IN} = 0 V or V_{DD}
Logic 1 Input Current				
(All Digital Inputs), SDATA, SCLOCK	±10	±10	µA max	V_{IN} = V_{DD}
	±1	±1	µA typ	V_{IN} = V_{DD}
Logic 0 Input Current (Ports 1, 2, 3) SDATA, SCLOCK	–75	–25	µA max	
	–40	–15	µA typ	V_{IL} = 450 mV
Logic 1 to Logic 0 Transition Current (Ports 2 and 3)	–660	–250	µA max	V_{IL} = 2 V
	–400	–140	µA typ	V_{IL} = 2 V
RESET	±10	±10	µA max	V_{IN} = 0 V
	10	5	µA min	V_{IN} = 5 V, 3 V Internal Pull Down
	105	35	µA max	V_{IN} = 5 V, 3 V Internal Pull Down

Parameter	V_{DD} = 5 V	V_{DD} = 3 V	Unit	Test Conditions/Comments
LOGIC INPUTS[4]				
INPUT VOLTAGES				
All Inputs Except SCLOCK, SDATA, RESET, and XTAL1				
VINL, Input Low Voltage	0.8	0.4	V max	
VINH, Input High Voltage	2.0	2.0	V min	
SDATA				
VINL, Input Low Voltage	0.8	0.8	V max	
VINH, Input High Voltage	2.0	2.0	V min	
SCLOCK and RESET ONLY[4]				
(Schmitt-Triggered Inputs)				
V_{T+}	1.3	0.95	V min	
	3.0	0.25	V max	
V_{T-}	0.8	0.4	V min	
	1.4	1.1	V max	
$V_{T+} - V_{T-}$	0.3	0.3	V min	
	0.85	0.85	V max	
CRYSTAL OSCILLATOR				
Logic Inputs, XTAL1 Only				
V_{INL}, Input Low Voltage	0.8	0.4	V typ	
V_{INH}, Input High Voltage	3.5	2.5	V typ	
XTAL1 Input Capacitance	18	18	pF typ	
XTAL2 Output Capacitance	18	18	pF typ	
MCU CLOCK RATE	16.78	8.38	MHz max	ADuC842/ADuC843 Only
	20	8.38	MHz max	ADuC841 Only
DIGITAL OUTPUTS				
Output High Voltage (V_{OH})	2.4		V min	V_{DD} = 4.5 V to 5.5 V
	4		V typ	I_{SOURCE} = 80 µA
		2.4	V min	V_{DD} = 2.7 V to 3.3 V
		2.6	V typ	I_{SOURCE} = 20 µA
Output Low Voltage (V_{OL})				
ALE, Ports 0 and 2	0.4	0.4	V max	I_{SINK} = 1.6 mA
	0.2	0.2	V typ	I_{SINK} = 1.6 mA
Port 3	0.4	0.4	V max	I_{SINK} = 4 mA
SCLOCK/SDATA	0.4	0.4	V max	I_{SINK} = 8 mA, I^2C Enabled
Floating State Leakage Current[4]	±10	±10	µA max	
	±1	±1	µA typ	
STARTUP TIME				At any core CLK
At Power-On	500	500	ms typ	
From Idle Mode	100	100	µs typ	
From Power-Down Mode				
Wake-up with $\overline{INT0}$ Interrupt	150	400	µs typ	
Wake-up with SPI/I^2C Interrupt	150	400	µs typ	
Wake-up with External RESET	150	400	µs typ	
After External RESET in Normal Mode	30	30	ms typ	
After WDT Reset in Normal Mode	3	3	ms typ	Controlled via WDCON SFR

Parameter	V_{DD} = 5 V	V_{DD} = 3 V	Unit	Test Conditions/Comments
POWER REQUIREMENTS[19, 20]				
Power Supply Voltages				
AV_{DD}/DV_{DD} – AGND		2.7	V min	AV_{DD}/DV_{DD} = 3 V nom
		3.6	V max	
	4.75		V min	AV_{DD}/DV_{DD} = 5 V nom
	5.25		V max	
Power Supply Currents **Normal** Mode[21]				
DV_{DD} Current[4]	10	4.5	mA typ	Core CLK = 2.097 MHz
AV_{DD} Current	1.7	1.7	mA max	Core CLK = 2.097 MHz
DV_{DD} Current	38	12	mA max	Core CLK = 16.78MHz/8.38 MHz 5 V/3 V
	33	10	mA typ	Core CLK = 16.78MHz/8.38 MHz 5 V/3 V
AV_{DD} Current	1.7	1.7	mA max	Core CLK = 16.78MHz/8.38 MHz 5 V/3 V
DV_{DD} Current[4]	45	N/A	mA max	Core CLK = 20MHz **ADuC841 Only**
Power Supply Currents **Idle** Mode[21]				
DV_{DD} Current	4.5	2.2	mA typ	Core CLK = 2.097 MHz
AV_{DD} Current	3	2	µA typ	Core CLK = 2.097 MHz
DV_{DD} Current[4]	12	5	mA max	Core CLK = 16.78 MHz/8.38 MHz 5 V/3 V
	10	3.5	mA typ	Core CLK = 16.78 MHz/8.38 MHz 5 V/3 V
AV_{DD} Current	3	2	µA typ	Core CLK = 16.78 MHz/8.38 MHz 5 V/3 V
Power Supply Currents **Power-Down** Mode[21]				Core CLK = any frequency
DV_{DD} Current	28	18	µA max	Oscillator Off / TIMECON.1 = 0
	20	10	µA typ	
AV_{DD} Current	2	1	µA typ	Core CLK = any frequency, **ADuC841 Only**
DV_{DD} Current[4]	3	1	mA max	TIMECON.1 = 1
DV_{DD} Current[4]	50	22	µA max	Core CLK = any frequency
	40	15	µA typ	**ADuC842/ADuC843 Only,** oscillator on
Typical Additional Power Supply Currents				
PSM Peripheral	15	10	µA typ	AV_{DD} = DV_{DD}
ADC[4]	1.0	1.0	mA min	MCLK Divider = 32
	2.8	1.8	mA max	MCLK Divider = 2
DAC	150	130	µA typ	

See footnotes on the next page.

[1] Temperature Range –40°C to +85°C.
[2] ADC linearity is guaranteed during normal MicroConverter core operation.
[3] ADC LSB size = $V_{REF}/2^{12}$, that is, for internal V_{REF} = 2.5 V, 1 LSB = 610 µV, and for external V_{REF} = 1 V, 1 LSB = 244 µV.
[4] These numbers are not production tested but are supported by design and/or characterization data on production release.
[5] Offset and gain error and offset and gain error match are measured after factory calibration.
[6] Based on external ADC system components, the user may need to execute a system calibration to remove additional external channel errors to achieve these specifications.
[7] SNR calculation includes distortion and noise components.
[8] Channel-to-channel crosstalk is measured on adjacent channels.
[9] The temperature monitor gives a measure of the die temperature directly; air temperature can be inferred from this result.
[10] DAC linearity is calculated using:
Reduced code range of 100 to 4095, 0 V to V_{REF} range.
Reduced code range of 100 to 3945, 0 V to V_{DD} range.
DAC output load = 10 kΩ and 100 pF.
[11] DAC differential nonlinearity specified on 0 V to V_{REF} and 0 V to V_{DD} ranges.
[12] DAC specification for output impedance in the unbuffered case depends on DAC code.
[13] DAC specifications for I_{SINK}, voltage output settling time, and digital-to-analog glitch energy depend on external buffer implementation in unbuffered mode. DAC in unbuffered mode tested with OP270 external buffer, which has a low input leakage current.
[14] Measured with C_{REF} pin decoupled with 0.47 µF capacitor to ground. Power-up time for the internal reference is determined by the value of the decoupling capacitor chosen for the C_{REF} pin.
[15] When using an external reference device, the internal band gap reference input can be bypassed by setting the ADCCON1.6 bit.
[16] Flash/EE memory reliability characteristics apply to both the Flash/EE program memory and the Flash/EE data memory.
[17] Endurance is qualified to 100,000 cycles as per JEDEC Std. 22 method A117 and measured at –40°C, +25°C, and +85°C. Typical endurance at 25°C is 700,000 cycles.
[18] Retention lifetime equivalent at junction temperature (T_J) = 55°C as per JEDEC Std. 22 method A117. Retention lifetime based on an activation energy of 0.6 eV derates with junction temperature as shown in Figure 38 in the Flash/EE Memory Reliability section.
[19] Power supply current consumption is measured in normal, idle, and power-down modes under the following conditions:

Normal Mode:	Reset = 0.4 V, digital I/O pins = open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), core executing internal software loop.
Idle Mode:	Reset = 0.4 V, digital I/O pins = open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), PCON.0 = 1, core execution suspended in idle mode.
Power-Down Mode:	Reset = 0.4 V, all Port 0 pins = 0.4 V, All other digital I/O and Port 1 pins are open circuit, Core Clk changed via CD bits in PLLCON (ADuC842/ADuC843), PCON.0 = 1, core execution suspended in power-down mode, OSC turned on or off via OSC_PD bit (PLLCON.7) in PLLCON SFR (ADuC842/ADuC843).

[20] DV_{DD} power supply current increases typically by 3 mA (3 V operation) and 10 mA (5 V operation) during a Flash/EE memory program or erase cycle.
[21] Power supply currents are production tested at 5.25 V and 3.3 V for a 5 V and 3 V part, respectively.

ABSOLUTE MAXIMUM RATINGS

Table 2. T_A = 25°C, unless otherwise noted

Parameter	Rating
AV_{DD} to DV_{DD}	−0.3 V to +0.3 V
AGND to DGND	−0.3 V to +0.3 V
DV_{DD} to DGND, AV_{DD} to AGND	−0.3 V to +7 V
Digital Input Voltage to DGND	−0.3 V to DV_{DD} + 0.3 V
Digital Output Voltage to DGND	−0.3 V to DV_{DD} + 0.3 V
V_{REF} to AGND	−0.3 V to AV_{DD} + 0.3 V
Analog Inputs to AGND	−0.3 V to AV_{DD} + 0.3 V
Operating Temperature Range, Industrial ADuC841BS, ADuC842BS, ADuC843BS, ADuC841BCP, ADuC842BCP, ADuC843BCP	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
θ_{JA} Thermal Impedance (ADuC84xBS)	90°C/W
θ_{JA} Thermal Impedance (ADuC84xBCP)	52°C/W
Lead Temperature, Soldering	
Vapor Phase (60 sec)	215°C
Infrared (15 sec)	220°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

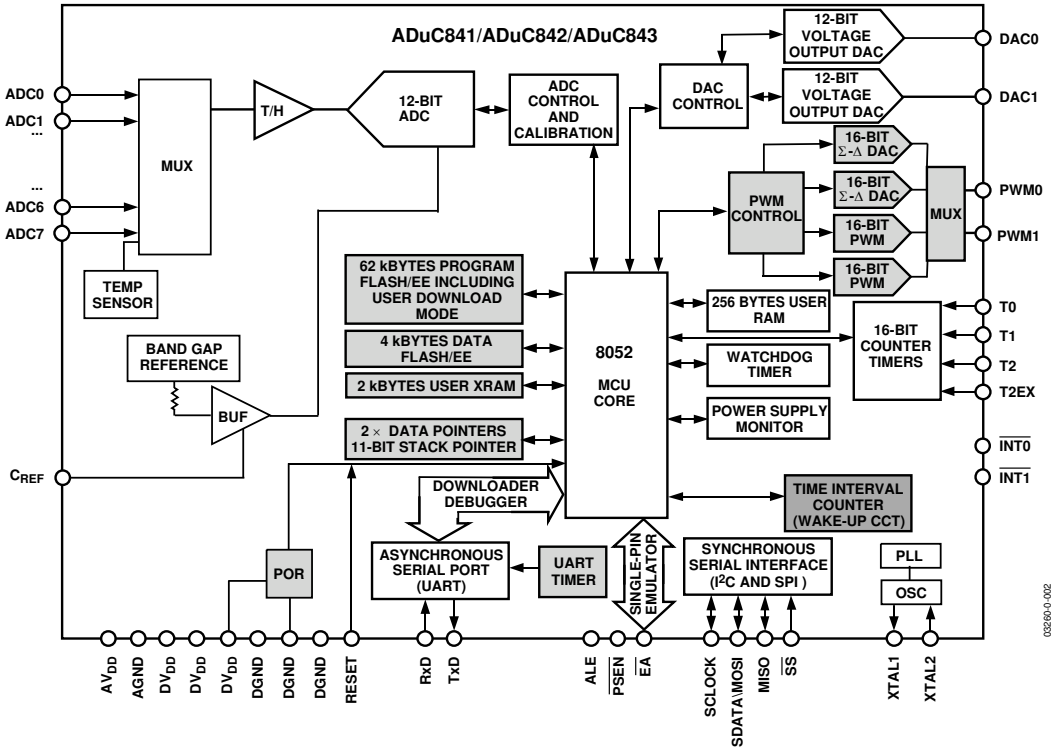

Figure 2. ADuC841/ADuC842/ADuC843 Block Diagram (Shaded Areas are Features Not Present on the ADuC812), No DACs on ADuC843, PLL on ADuC842/ADuC843 Only.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

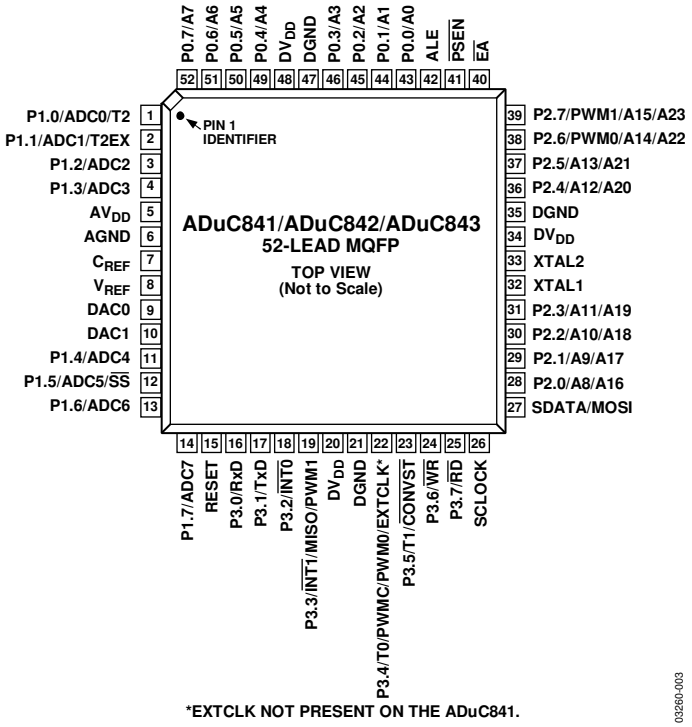

Figure 3. 52-Lead MQFP Pin Configuration

Table 3. 52-Lead MQFP Pin Function Descriptions

Pin No.	Mnemonic	Type[1]	Description
1	P1.0/ADC0/T2	I	Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input (ADC0). Channel selection is via ADCCON2 SFR. Timer 2 Digital Input (T2). Input to Timer/Counter 2. When enabled, Counter 2 is incremented in response to a 1 to 0 transition of the T2 input.
2	P1.1/ADC1/T2EX	I	Input Port 1 (P1.1). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input 1 (ADC1). Channel selection is via ADCCON2 SFR. Capture/Reload Trigger for Counter 2 (T2EX). T2EX is a digital input. This pin also functions as an up/down control input for Counter 2.
3	P1.2/ADC2	I	Input Port 1 (P1.2). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input (ADC2). Channel selection is via ADCCON2 SFR.
4	P1.3/ADC3	I	Input Port 1 (P1.3). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input (ADC3). Channel selection is via ADCCON2 SFR.
5	AV_{DD}	P	Analog Positive Supply Voltage. 3 V or 5 V nominal.
6	AGND	G	Analog Ground. AGND is the ground reference point for the analog circuitry.
7	C_{REF}	I/O	Decoupling Input for On-Chip Reference. Connect a 0.47 µF capacitor between this pin and AGND.
8	V_{REF}	NC	Not Connected. This was a reference output on the ADuC812; use the C_{REF} pin instead.
9	DAC0	O	Voltage Output from DAC0. This pin is a no connect on the ADuC843.
10	DAC1	O	Voltage Output from DAC1. This pin is a no connect on the ADuC843.

Pin No.	Mnemonic	Type[1]	Description
11	P1.4/ADC4		Input Port 1 (P1.4). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 4 (ADC4). Channel selection is via ADCCON2 SFR.
12	P1.5/ADC5/$\overline{SS}$	I	Input Port 1 (P1.5). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 5 (ADC5). Channel selection is via ADCCON2 SFR.
			Slave Select Input for the SPI Interface ($\overline{SS}$).
13	P1.6/ADC6	I	Input Port 1 (P1.6). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 6 (ADC6). Channel selection is via ADCCON2 SFR.
14	P1.7/ADC7	I	Input Port 1(P1.7). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 7 (ADC7). Channel selection is via ADCCON2 SFR.
15	RESET	I	Reset. Digital Input. A high level on this pin for 24 master clock cycles while the oscillator is running resets the device.
16	P3.0/RxD	I/O	Input/Output Port 3 (P3.0). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Receiver Data Input (Asynchronous) or Data Input/Output (Synchronous) of the Serial (UART) Port (RxD).
17	P3.1/TxD	I/O	Input/Output Port 3 (P3.1). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Transmitter Data Output (Asynchronous) or Clock Output (Synchronous) of the Serial (UART) Port (TxD).
18	P3.2/$\overline{INT0}$	I/O	Input/Output Port 3 (P3.2). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 0 ($\overline{INT0}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 0.
19	P3.3/$\overline{INT1}$/MISO/PWM1	I/O	Input/Output Port 3 (P3.3). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 1 ($\overline{INT1}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 1.
			SPI Master Input/Slave Output Data I/O Pin for SPI Serial Interface (MISO).
			PWM 1 Voltage Output (PWM1). See the CFG841/CFG842 register for further information.
20, 34, 48	DV_{DD}	P	Digital Positive Supply Voltage. 3 V or 5 V nominal.
21, 35, 47	DGND	G	Digital Ground. DGND is the ground reference point for the digital circuitry.

Pin No.	Mnemonic	Type[1]	Description
22	P3.4/T0/PWMC/PWM0/EXTCLK	I/O	Input/Output Port 3 (P3.4). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Timer/Counter 0 Input (T0). PWM Clock Input (PWMC). PWM 0 Voltage Output (PWM0). PWM outputs can be configured to use Port 2.6 and Port 2.7 or Port 3.4 and Port 3.3. Input for External Clock Signal (EXTCLK). This pin function must be enabled via the CFG842 register.
23	P3.5/T1/$\overline{\text{CONVST}}$	I/O	Input/Output Port 3 (P3.5). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Timer/Counter 1 Input (T1). Active Low Convert Start Logic Input for the ADC Block When the External Convert Start Function is Enabled ($\overline{\text{CONVST}}$). A low to high transition on this input puts the track-and-hold into hold mode and starts the conversion.
24	P3.6/$\overline{\text{WR}}$	I/O	Input/Output Port 3 (P3.6). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Write Control Signal, Logic Output ($\overline{\text{WR}}$). Latches the data byte from Port 0 into the external data memory.
25	P3.7/$\overline{\text{RD}}$	I/O	Input/Output Port 3 (P3.7). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Read Control Signal, Logic Output ($\overline{\text{RD}}$). Enables the external data memory to Port 0.
26	SCLOCK	I/O	Serial Clock Pin for I^2C-Compatible Clock or for SPI Serial Interface Clock.
27	SDATA/MOSI	I/O	User Selectable, I^2C Compatible, or SPI Data Input/Output Pin (SDATA). SPI Master Output/Slave Input Data I/O Pin for SPI Interface (MOSI).
28	P2.0/A8/A16	I/O	Input/Output Port 2 (P2.0). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A8). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A16). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
29	P2.1/A9/A17	I/O	Input/Output Port 2 (P2.1). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A9). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A17). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
30	P2.2/A10/A18	I/O	Input/Output Port 2 (P2.2). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A10). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A18). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.

Pin No.	Mnemonic	Type[1]	Description
31	P2.3/A11/A19	I/O	Input/Output Port 2 (P2.3). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A11). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A19). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
32	XTAL1	I	Input to the Inverting Oscillator Amplifier.
33	XTAL2	O	Output of the Inverting Oscillator Amplifier.
36	P2.4/A12/A20	I/O	Input/Output Port 2 (P2.4). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A12). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A20). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
37	P2.5/A13/A21	I/O	Input/Output Port 2 (P2.5). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A13). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A21). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
38	P2.6/PWM0/A14/A22	I/O	Input/Output Port 2 (P2.6). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. PWM 0 Voltage Output (PWM0). PWM outputs can be configured to use Port 2.6 and Port 2.7 or Port 3.4 and Port 3.3. External Memory Addresses (A14). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A22). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
39	P2.7/PWM1/A15/A23	I/O	Input/Output Port 2 (P2.7). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. PWM 1 Voltage Output (PWM1). See the CFG841/CFG842 register for further information. External Memory Addresses (A15). Port 2 emits the middle-order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A23). Port 2 emits the high-order address bytes during accesses to the external 24-bit external data memory space.
40	$\overline{EA}$	I	External Access Enable, Logic Input. When held high, this input enables the device to fetch code from internal program memory locations. The devices do not support external code memory. Do not leave this pin floating.
41	$\overline{PSEN}$	O	Program Store Enable, Logic Output. This pin remains low during internal program execution. $\overline{PSEN}$ enables serial download mode when pulled low through a resistor on power-up or reset. On reset, this pin momentarily becomes an input and the status of the pin is sampled. If there is no pull-down resistor in place, the pin goes momentarily high and then user code executes. If a pull-down resistor is in place, the embedded serial download/debug kernel executes.
42	ALE	O	Address Latch Enable, Logic Output. This output latches the low byte and page byte for 24-bit address space accesses of the address into external data memory.

Pin No.	Mnemonic	Type[1]	Description
43	P0.0/A0	I/O	Input/Output Port 0 (P0.0). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A0). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
44	P0.1/A1	I/O	Input/Output Port 0 (P0.1). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A1). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
45	P0.2/A2	I/O	Input/Output Port 0 (P0.2). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A2). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
46	P0.3/A3	I/O	Input/Output Port 0 (P0.3).Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A3). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
49	P0.4/A4	I/O	Input/Output Port 0 (P0.4). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A4). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
50	P0.5/A5	I/O	Input/Output Port 0 (P0.5). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A5). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
51	P0.6/A6	I/O	Input/Output Port 0 (P0.6). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A6). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
52	P0.7/A7	I/O	Input/Output Port 0 (P0.7). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A7). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.

[1] P = power, G = ground, I= input, O = output., NC = no connect.

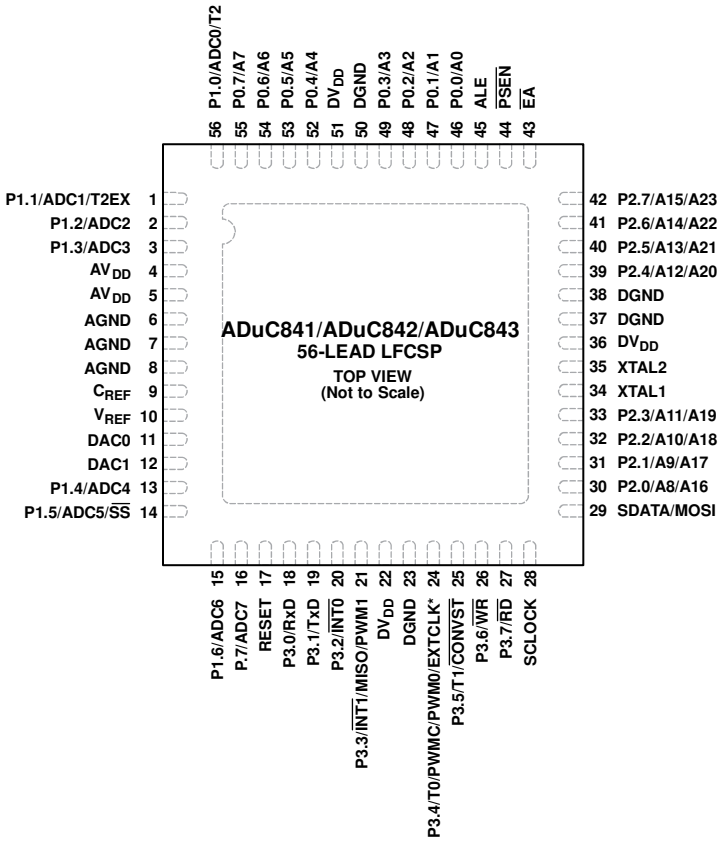

Figure 4. 56-Lead LFCSP Pin Configuration

Table 4. 56-Lead LFCSP Pin Function Descriptions

Pin No.	Mnemonic	Type[1]	Description
1	P1.1/ADC1/T2EX	I	Input Port 1 (P1.1). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 1 (ADC1). Channel selection is via ADCCON2 SFR.
			Capture/Reload Trigger for Counter 2 (T2EX). Digital Input. This pin also functions as an up/down control input for Counter 2.
2	P1.2/ADC2	I	Input Port 1 (P1.2). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input (ADC2). Channel selection is via ADCCON2 SFR.
3	P1.3/ADC3	I	Input Port 1 (P1.3). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input (ADC3). Channel selection is via ADCCON2 SFR.
4, 5	AV_{DD}	P	Analog Positive Supply Voltage. 3 V or 5 V nominal.
6, 7, 8	AGND	G	Analog Ground. AGND is the ground reference point for the analog circuitry.
9	C_{REF}	I/O	Decoupling Input for On-Chip Reference. Connect a 0.47 µF capacitor between this pin and AGND.
10	V_{REF}	NC	Not Connected. This was a reference output on the ADuC812; use the C_{REF} pin instead.
11	DAC0	O	Voltage Output from DAC0. This pin is a no connect on the ADuC843.

Pin No.	Mnemonic	Type[1]	Description
12	DAC1	O	Voltage Output from DAC1. This pin is a no connect on the ADuC843.
13	P1.4/ADC4		Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 4 (ADC4). Channel selection is via ADCCON2 SFR.
14	P1.5/ADC5/$\overline{SS}$	I	Input Port 1 (P1.5). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 5 (ADC5). Channel selection is via ADCCON2 SFR.
			Slave Select Input for the SPI Interface ($\overline{SS}$).
15	P1.3/ADC6	I	Input Port 1 (P1.3). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 6 (ADC6). Channel selection is via ADCCON2 SFR.
16	P1.7/ADC7	I	Input Port 1(P1.7). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit.
			Single-Ended Analog Input 7 (ADC7). Channel selection is via ADCCON2 SFR.
17	RESET	I	Reset. Digital Input. A high level on this pin for 24 master clock cycles while the oscillator is running resets the device.
18	P3.0/RxD	I/O	Input/Output Port 3 (P3.0). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Receiver Data Input (Asynchronous) or Data Input/Output (Synchronous) of the Serial (UART) Port (RxD).
19	P3.1/TxD	I/O	Input/Output Port 3 (P3.1). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Transmitter Data Output (Asynchronous) or Clock Output (Synchronous) of the Serial (UART) Port (TxD).
20	P3.2/$\overline{INT0}$	I/O	Input/Output Port 3 (P3.2). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 0 ($\overline{INT0}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 0.
21	P3.3/$\overline{INT1}$/MISO/PWM1	I/O	Input/Output Port 3 (P3.3). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors.
			Interrupt 1 ($\overline{INT1}$). Programmable edge or level triggered interrupt input; can be programmed to one of two priority levels. This pin can also be used as a gate control input to Timer 1.
			SPI Master Input/Slave Output Data I/O Pin for SPI Serial Interface (MISO).
			PWM 1 Voltage Output (PWM1). See the CFG841/CFG842 register for further information.
22, 36, 51	DV_{DD}	P	Digital Positive Supply Voltage. 3 V or 5 V nominal.
23, 37, 38, 50	DGND	G	Digital Ground. DGND is the ground reference point for the digital circuitry.

Pin No.	Mnemonic	Type[1]	Description
24	P3.4/T0/PWMC/PWM0/EXTCLK	I/O	Input/Output Port 3 (P3.4). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Timer/Counter 0 Input (T0). PWM Clock Input (PWMC). PWM 0 Voltage Output (PWM0). PWM outputs can be configured to use Port 2.6 and Port 2.7 or Port 3.4 and Port 3.3. Input for External Clock Signal (EXTCLK). This pin function must be enabled via the CFG842 register.
25	P3.5/T1/$\overline{\text{CONVST}}$	I/O	Input/Output Port 3 (P3.5). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Timer/Counter 1 Input (T1). Active Low Convert Start Logic Input for the ADC Block when the External Convert Start Function is Enabled ($\overline{\text{CONVST}}$). A low to high transition on this input puts the track-and-hold into hold mode and starts the conversion.
26	P3.6/$\overline{\text{WR}}$	I/O	Input/Output Port 3 (P3.6). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Write Control Signal, Logic Output ($\overline{\text{WR}}$). Latches the data byte from Port 0 into the external data memory.
27	P3.7/$\overline{\text{RD}}$	I/O	Input/Output Port 3 (P3.7). Port 3 is a bidirectional port with internal pull-up resistors. Port 3 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 3 pins being pulled externally low source current because of the internal pull-up resistors. Read Control Signal, Logic Output ($\overline{\text{RD}}$). Enables the external data memory to Port 0.
28	SCLOCK	I/O	Serial Clock Pin for I^2C-Compatible Clock or for SPI Serial Interface Clock.
29	SDATA/MOSI	I/O	User Selectable, I^2C Compatible, or SPI Data Input/Output Pin (SDATA). SPI Master Output/Slave Input Data I/O Pin for SPI Interface (MOSI).
30	P2.0/A8/A16	I/O	Input/Output Port 2 (P2.0). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A8). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A16). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
31	P2.1/A9/A17	I/O	Input/Output Port 2 (P2.1). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A9). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A17). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
32	P2.2/A10/A18	I/O	Input/Output Port 2 (P2.2). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A10). Port 2 emits the middle address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A18). Port 2 emits the high-order address byte during accesses to the external 24-bit external data memory space.

Pin No.	Mnemonic	Type[1]	Description
33	P2.3/A11/A19	I/O	Input/Output Port 2 (P2.3). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A11). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A19). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
34	XTAL1	I	Input to the Inverting Oscillator Amplifier.
35	XTAL2	O	Output of the Inverting Oscillator Amplifier.
39	P2.4/A12/A20	I/O	Input/Output Port 2 (P2.4). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A12). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A20). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
40	P2.5/A13/A21	I/O	Input/Output Port 2 (P2.5). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A13). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A21). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
41	P2.6/A14/A22	I/O	Input/Output Port 2 (P2.6). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A14). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A22). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
42	P2.7/A15/A23	I/O	Input/Output Port 2 (P2.7). Port 2 is a bidirectional port with internal pull-up resistors. Port 2 pins that have 1s written to them are pulled high by the internal pull-up resistors, and in that state can be used as inputs. As inputs, Port 2 pins being pulled externally low source current because of the internal pull-up resistors. External Memory Addresses (A15). Port 2 emits the middle order address byte during accesses to the external 24-bit external data memory space. External Memory Addresses (A23). Port 2 emits the high order address byte during accesses to the external 24-bit external data memory space.
43	$\overline{EA}$	I	External Access Enable, Logic Input. When held high, this input enables the device to fetch code from internal program memory locations. The devices do not support external code memory. Do not leave this pin floating.
44	$\overline{PSEN}$	O	Program Store Enable, Logic Output. This pin remains low during internal program execution. $\overline{PSEN}$ enables serial download mode when pulled low through a resistor on power-up or reset. On reset, this pin momentarily becomes an input and the status of the pin is sampled. If there is no pull-down resistor in place, the pin goes momentarily high and then user code executes. If a pull-down resistor is in place, the embedded serial download/debug kernel executes.
45	ALE	O	Address Latch Enable, Logic Output. This output latches the low byte and page byte for 24-bit address space accesses of the address into external data memory.

Pin No.	Mnemonic	Type[1]	Description
46	P0.0/A0	I/O	Input/Output Port 0 (P0.0). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A0). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-ups when emitting 1s.
47	P0.1/A1	I/O	Input/Output Port 0 (P0.1). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A1). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
48	P0.2/A2	I/O	Input/Output Port 0 (P0.2). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A2). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
49	P0.3/A3	I/O	Input/Output Port 0 (P0.3). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A3). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
52	P0.4/A4	I/O	Input/Output Port 0 (P0.4). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A4). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
53	P0.5/A5	I/O	Input/Output Port 0 (P0.5). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A5). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
54	P0.6/A6	I/O	Input/Output Port 0 (P0.6). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A6). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
55	P0.7/A7	I/O	Input/Output Port 0 (P0.7). Port 0 is an 8-bit open-drain bidirectional I/O port. Port 0 pins that have 1s written to them float, and in that state can be used as high impedance inputs. External Memory Address (A7). Port 0 is also the multiplexed low order address and data bus during accesses to external data memory. In this application, it uses strong internal pull-up resistors when emitting 1s.
56	P1.0/ADC0/T2	I	Input Port 1 (P1.0). Port 1 is an 8-bit input port only. Unlike the other ports, Port 1 defaults to analog input mode. To configure this port pin as a digital input, write a 0 to the port bit. Single-Ended Analog Input (ADC0). Channel selection is via ADCCON2 SFR. Timer 2 Digital Input (T2). Input to Timer/Counter 2. When enabled, Counter 2 is incremented in response to a 1-to-0 transition of the T2 input.
	EPAD		Exposed Pad. The LFCSP has an exposed pad that must be soldered to the metal plate on the printed circuit board (PCB) for mechanical reasons and to DGND.

[1] P = power, G = ground, I = input, O = output, and NC = no connect.

TERMINOLOGY

ADC SPECIFICATIONS

Integral Nonlinearity

The maximum deviation of any code from a straight line passing through the endpoints of the ADC transfer function. The endpoints of the transfer function are zero scale, a point ½ LSB below the first code transition, and full scale, a point ½ LSB above the last code transition.

Differential Nonlinearity

The difference between the measured and the ideal 1 LSB change between any two adjacent codes in the ADC.

Offset Error

The deviation of the first code transition (0000 . . . 000) to (0000 . . . 001) from the ideal, that is, +½ LSB.

Gain Error

The deviation of the last code transition from the ideal AIN voltage (Full Scale – ½ LSB) after the offset error has been adjusted out.

Signal-to-(Noise + Distortion) Ratio

The measured ratio of signal to (noise + distortion) at the output of the ADC. The signal is the rms amplitude of the fundamental. Noise is the rms sum of all nonfundamental signals up to half the sampling frequency ($f_S/2$), excluding dc. The ratio depends on the number of quantization levels in the digitization process; the more levels, the smaller the quantization noise. The theoretical signal-to-(noise + distortion) ratio for an ideal N-bit converter with a sine wave input is given by

$$Signal\text{-}to\text{-}(Noise + Distortion) = (6.02N + 1.76)\ dB$$

Thus for a 12-bit converter, this is 74 dB.

Total Harmonic Distortion (THD)

The ratio of the rms sum of the harmonics to the fundamental.

DAC SPECIFICATIONS

Relative Accuracy

Relative accuracy or endpoint linearity is a measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero error and full-scale error.

Voltage Output Settling Time

The amount of time it takes for the output to settle to a specified level for a full-scale input change.

Digital-to-Analog Glitch Impulse

The amount of charge injected into the analog output when the inputs change state. It is specified as the area of the glitch in nV-sec.

TYPICAL PERFORMANCE CHARACTERISTICS

The typical performance plots presented in this section illustrate typical performance of the ADuC841/ADuC842/ADuC843 under various operating conditions.

Figure 5 and Figure 6 show typical ADC integral nonlinearity (INL) errors from ADC Code 0 to Code 4095 at 5 V and 3 V supplies, respectively. The ADC is using its internal reference (2.5 V) and is operating at a sampling rate of 152 kHz; the typical worst-case errors in both plots are just less than 0.3 LSB. Figure 7 and Figure 8 also show ADC INL at a higher sampling rate of 400 kHz. Figure 9 and Figure 10 show the variation in worst-case positive (WCP) INL and worst-case negative (WCN) INL versus external reference input voltage.

Figure 11 and Figure 12 show typical ADC differential nonlinearity (DNL) errors from ADC Code 0 to Code 4095 at 5 V and 3 V supplies, respectively. The ADC is using its internal reference (2.5 V) and is operating at a sampling rate of 152 kHz; the typical worst-case errors in both plots are just less than 0.2 LSB. Figure 13 and Figure 14 show the variation in worst-case positive (WCP) DNL and worst-case negative (WCN) DNL versus external reference input voltage.

Figure 15 shows a histogram plot of 10,000 ADC conversion results on a dc input with V_{DD} = 5 V. The plot illustrates an excellent code distribution pointing to the low noise performance of the on-chip precision ADC.

Figure 16 shows a histogram plot of 10,000 ADC conversion results on a dc input for V_{DD} = 3 V. The plot again illustrates a very tight code distribution of 1 LSB with the majority of codes appearing in one output pin.

Figure 17 and Figure 18 show typical FFT plots for the parts. These plots were generated using an external clock input. The ADC is using its internal reference (2.5 V), sampling a full-scale, 10 kHz sine wave test tone input at a sampling rate of 149.79 kHz. The resulting FFTs shown at 5 V and 3 V supplies illustrate an excellent 100 dB noise floor, 71 dB signal-to-noise ratio (SNR), and THD greater than –80 dB.

Figure 19 and Figure 20 show typical dynamic performance versus external reference voltages. Again, excellent ac performance can be observed in both plots with some roll-off being observed as V_{REF} falls below 1 V.

Figure 21 shows typical dynamic performance versus sampling frequency. SNR levels of 71 dB are obtained across the sampling range of the parts.

Figure 22 shows the voltage output of the on-chip temperature sensor versus temperature. Although the initial voltage output at 25°C can vary from part to part, the resulting slope of −1. 4 mV/°C is constant across all parts.

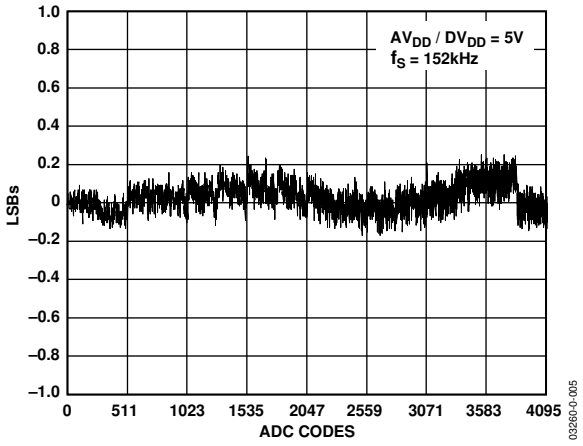

Figure 5. Typical INL Error, V_{DD} = 5 V, f_s = 152 kHz

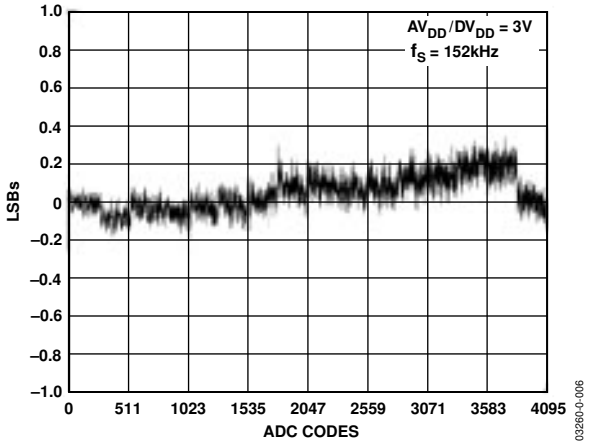

Figure 6. Typical INL Error, V_{DD} = 3 V, f_s = 152 kHz

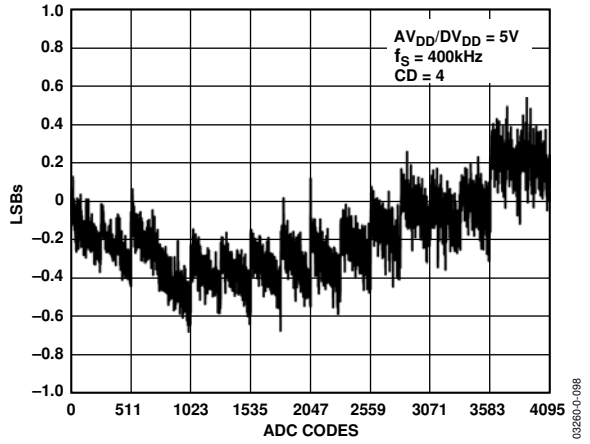

Figure 7. Typical INL Error, V_{DD} = 5 V, f_S = 400 kHz

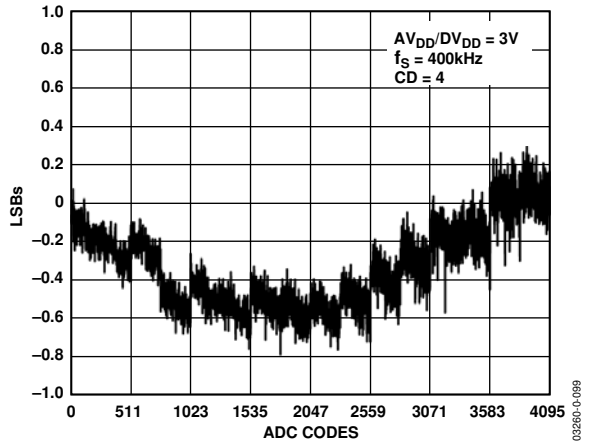

Figure 8. Typical INL Error, V_{DD} = 3 V, f_S = 400 kHz

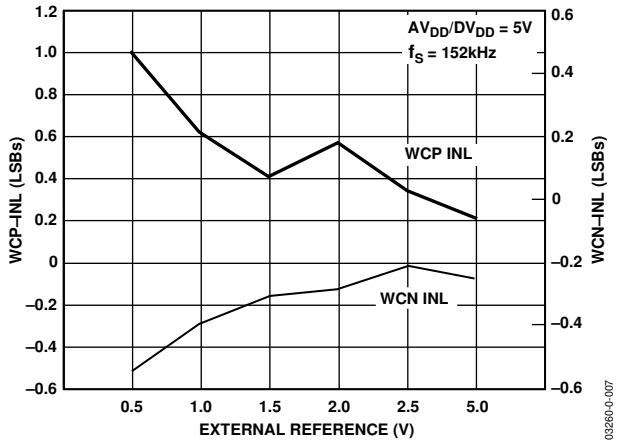

Figure 9. Typical Worst-Case INL Error vs. V_{REF}, V_{DD} = 5 V

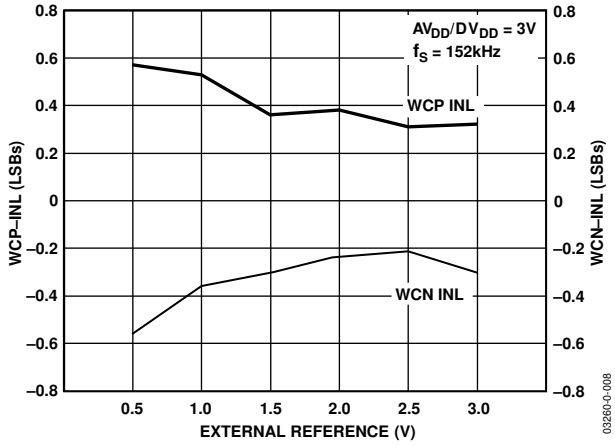

Figure 10. Typical Worst-Case INL Error vs. V_{REF}, V_{DD} = 3 V

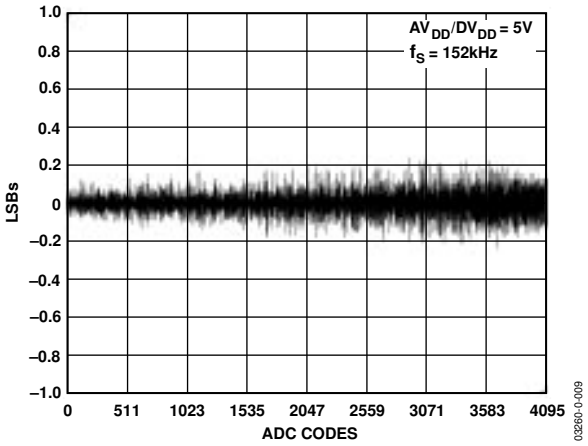

Figure 11. Typical DNL Error, V_{DD} = 5 V

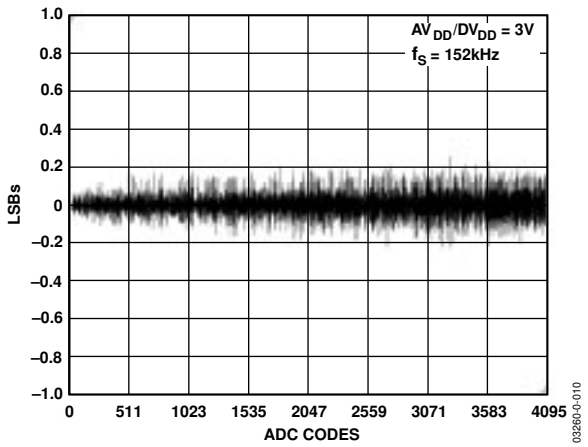

Figure 12. Typical DNL Error, V_{DD} = 3 V

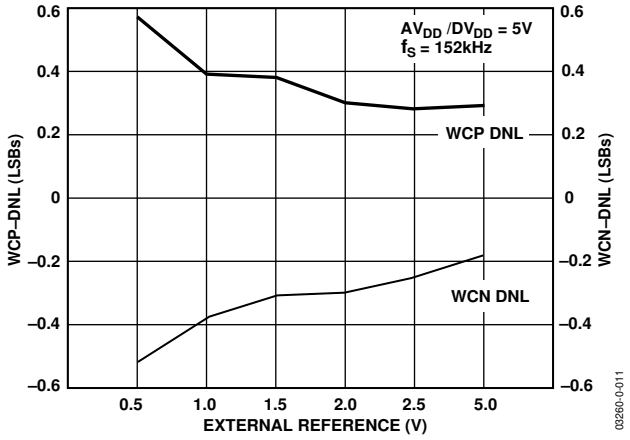

Figure 13. Typical Worst-Case DNL Error vs. V_{REF}, V_{DD} = 5 V

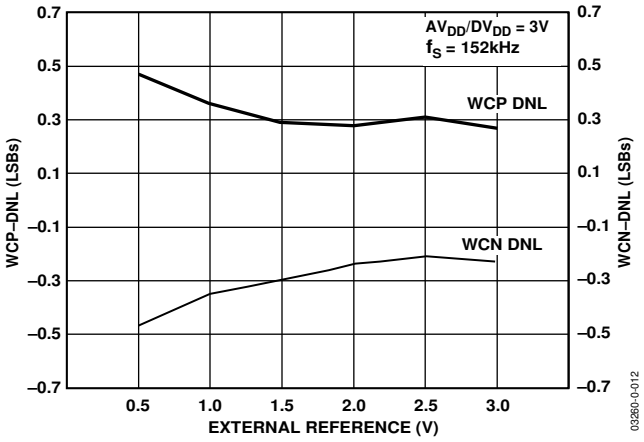

Figure 14. Typical Worst-Case DNL Error vs. V_{REF}, V_{DD} = 3 V

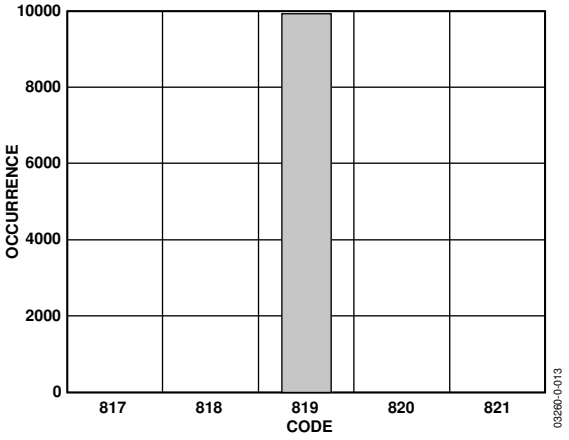

Figure 15. Code Histogram Plot, V_{DD} = 5 V

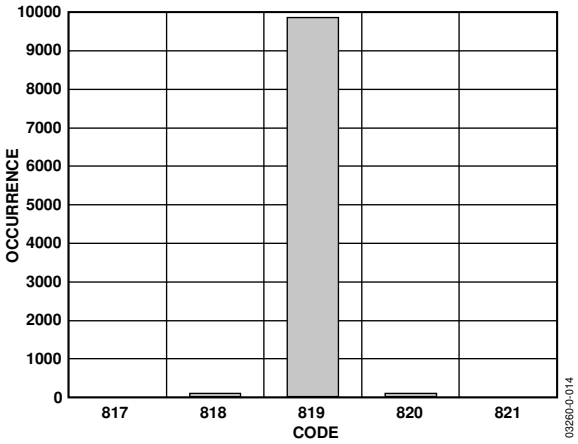

Figure 16. Code Histogram Plot, V_{DD} = 3 V

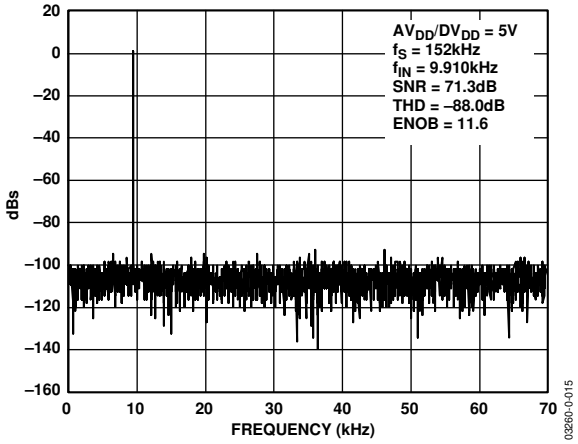

Figure 17. Dynamic Performance at V_{DD} = 5 V

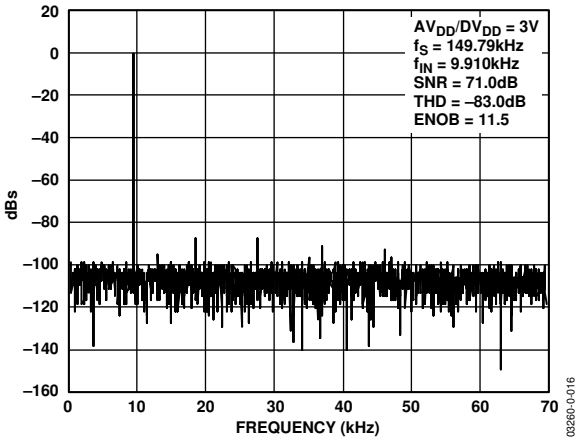

Figure 18. Dynamic Performance at V_{DD} = 3 V

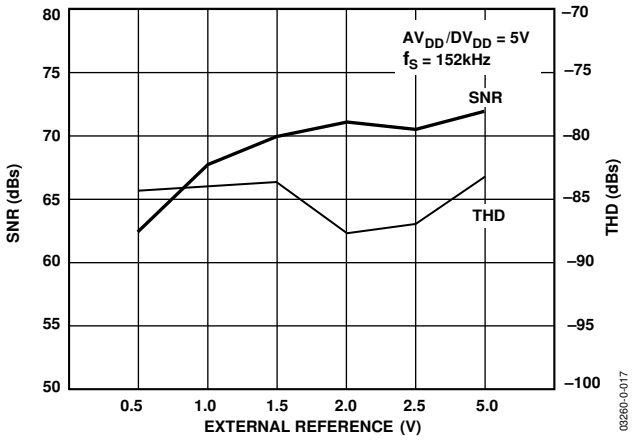

Figure 19. Typical Dynamic Performance vs. V_{REF}, V_{DD} = 5 V

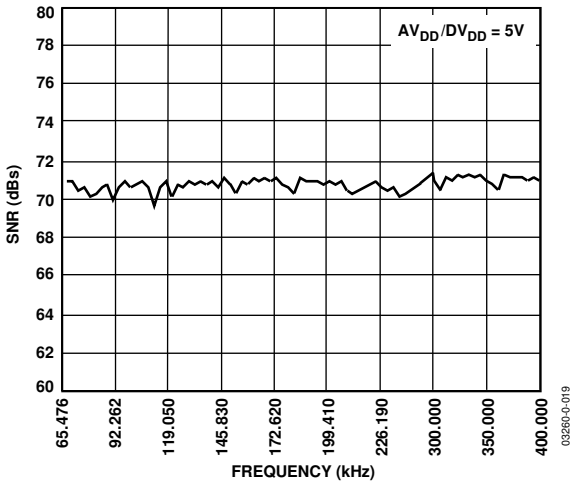

Figure 21. Typical Dynamic Performance vs. Sampling Frequency

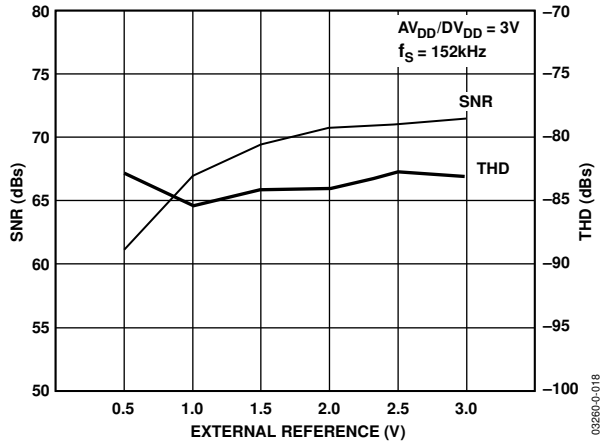

Figure 20. Typical Dynamic Performance vs. V_{REF}, V_{DD} = 3 V

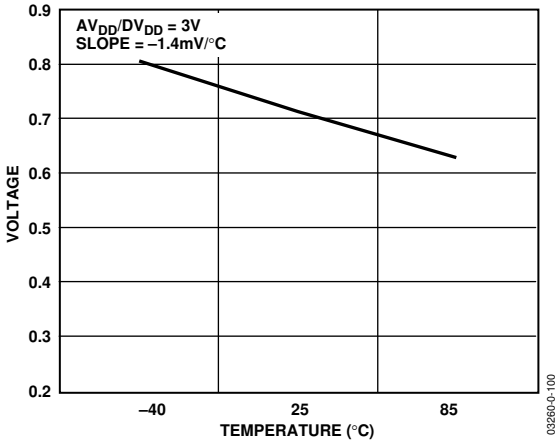

Figure 22. Typical Temperature Sensor Output vs. Temperature

GENERAL DESCRIPTION (*continued*)

The parts also incorporate additional analog functionality with two 12-bit DACs, power supply monitor, and a band gap reference. On-chip digital peripherals include two 16-bit Σ-Δ. DACs, a dual output 16-bit PWM, a watchdog timer, a time interval counter, three timers/counters, and three serial I/O ports (SPI, I²C, and UART).

On the ADuC812 and the ADuC832, the I²C and SPI interfaces share some of the same pins. For backwards compatibility, this is also the case for the ADuC841/ADuC842/ADuC843.

However, there is also the option to allow SPI operate separately on P3.3, P3.4, and P3.5, while I²C uses the standard pins. The I²C interface has also been enhanced to offer repeated start, general call, and quad addressing.

On-chip factory firmware supports in-circuit serial download and debug modes (via UART) as well as single-pin emulation mode via the $\overline{EA}$ pin. A functional block diagram of the parts is shown on the first page.

FUNCTIONAL DESCRIPTION

8052 INSTRUCTION SET

Table 5 documents the number of clock cycles required for each instruction. Most instructions are executed in one or two clock cycles, resulting in a 16 MIPS peak performance when operating at PLLCON = 00H on the ADuC842/ADuC843. On the ADuC841, 20 MIPS peak performance is possible with a 20 MHz external crystal.

Table 5. Instructions

Mnemonic	Description	Bytes	Cycles
Arithmetic			
ADD A,Rn	Add register to A	1	1
ADD A,@Ri	Add indirect memory to A	1	2
ADD A,dir	Add direct byte to A	2	2
ADD A,#data	Add immediate to A	2	2
ADDC A,Rn	Add register to A with carry	1	1
ADDC A,@Ri	Add indirect memory to A with carry	1	2
ADDC A,dir	Add direct byte to A with carry	2	2
ADD A,#data	Add immediate to A with carry	2	2
SUBB A,Rn	Subtract register from A with borrow	1	1
SUBB A,@Ri	Subtract indirect memory from A with borrow	1	2
SUBB A,dir	Subtract direct from A with borrow	2	2
SUBB A,#data	Subtract immediate from A with borrow	2	2
INC A	Increment A	1	1
INC Rn	Increment register	1	1
INC @Ri	Increment indirect memory	1	2
INC dir	Increment direct byte	2	2
INC DPTR	Increment data pointer	1	3
DEC A	Decrement A	1	1
DEC Rn	Decrement register	1	1
DEC @Ri	Decrement indirect memory	1	2
DEC dir	Decrement direct byte	2	2
MUL AB	Multiply A by B	1	9
DIV AB	Divide A by B	1	9
DA A	Decimal adjust A	1	2
Logic			
ANL A,Rn	AND register to A	1	1
ANL A,@Ri	AND indirect memory to A	1	2
ANL A,dir	AND direct byte to A	2	2
ANL A,#data	AND immediate to A	2	2
ANL dir,A	AND A to direct byte	2	2
ANL dir,#data	AND immediate data to direct byte	3	3
ORL A,Rn	OR register to A	1	1
ORL A,@Ri	OR indirect memory to A	1	2
ORL A,dir	OR direct byte to A	2	2
ORL A,#data	OR immediate to A	2	2
ORL dir,A	OR A to direct byte	2	2
ORL dir,#data	OR immediate data to direct byte	3	3
XRL A,Rn	Exclusive-OR register to A	1	1
XRL A,@Ri	Exclusive-OR indirect memory to A	2	2
XRL A,#data	Exclusive-OR immediate to A	2	2
XRL dir,A	Exclusive-OR A to direct byte	2	2

Mnemonic	Description	Bytes	Cycles
XRL A,dir	Exclusive-OR indirect memory to A	2	2
XRL dir,#data	Exclusive-OR immediate data to direct	3	3
CLR A	Clear A	1	1
CPL A	Complement A	1	1
SWAP A	Swap nibbles of A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1
Data Transfer			
MOV A,Rn	Move register to A	1	1
MOV A,@Ri	Move indirect memory to A	1	2
MOV Rn,A	Move A to register	1	1
MOV @Ri,A	Move A to indirect memory	1	2
MOV A,dir	Move direct byte to A	2	2
MOV A,#data	Move immediate to A	2	2
MOV Rn,#data	Move register to immediate	2	2
MOV dir,A	Move A to direct byte	2	2
MOV Rn, dir	Move register to direct byte	2	2
MOV dir, Rn	Move direct to register	2	2
MOV @Ri,#data	Move immediate to indirect memory	2	2
MOV dir,@Ri	Move indirect to direct memory	2	2
MOV @Ri,dir	Move direct to indirect memory	2	2
MOV dir,dir	Move direct byte to direct byte	3	3
MOV dir,#data	Move immediate to direct byte	3	3
MOV DPTR,#data	Move immediate to data pointer	3	3
MOVC A,@A+DPTR	Move code byte relative DPTR to A	1	4
MOVC A,@A+PC	Move code byte relative PC to A	1	4
MOVX A,@Ri	Move external (A8) data to A	1	4
MOVX A,@DPTR	Move external (A16) data to A	1	4
MOVX @Ri,A	Move A to external data (A8)	1	4
MOVX @DPTR,A	Move A to external data (A16)	1	4
PUSH dir	Push direct byte onto stack	2	2
POP dir	Pop direct byte from stack	2	2
XCH A,Rn	Exchange A and register	1	1
XCH A,@Ri	Exchange A and indirect memory	1	2
XCHD A,@Ri	Exchange A and indirect memory nibble	1	2
XCH A,dir	Exchange A and direct byte	2	2
Boolean			
CLR C	Clear carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement carry	1	1
CPL bit	Complement direct bit	2	2
ANL C,bit	AND direct bit and carry	2	2
ANL C,/bit	AND direct bit inverse to carry	2	2
ORL C,bit	OR direct bit and carry	2	2
ORL C,/bit	OR direct bit inverse to carry	2	2
MOV C,bit	Move direct bit to carry	2	2
MOV bit,C	Move carry to direct bit	2	2